EL465676034



Form PTO-1449 — U.S. DEPARTMENT OF COMMERCE, PATENT AND TRADEMARK OFFICE

# LIST OF ART CITED BY APPLICANT

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| ATTY. DOCKET M122-1427 | SERIAL NO. Filed Herewith |
|---|---|
| APPLICANT: Micron Technology, Inc. | |
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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| M122-1427 | ~~Filed Herewith~~ 09/559903 |
| APPLICANT: Micron Technology, Inc. | |
| FILING DATE: Filed Herewith | GROUP |

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| ATTY. DOCKET NO. | SERIAL NO. |
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| MI22-1427 | 09/559,903 |
| APPLICANT: Zhiping Yin et al. | |
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EXAMINER: J C Elmore — DATE CONSIDERED: 5/20/02

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ATTY. DOCKET NO. M122-1427 | SERIAL NO. 09/839,903

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APPLICANT Zhiping Yu et al.

FILING DATE April 26, 2000 | GROUP 2815

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EXAMINER [signature] DATE CONSIDERED 2/17/04

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